



ECTC
2022

May 31 - June 3, 2022

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Dear Attendee,

Thank you for attending the 2022 IEEE 72nd Electronic Components and Technology Conference, sponsored by the IEEE Electronics Packaging Society (EPS)!

I am pleased to let you know that this year's conference has been a resounding success; we received so much positive feedback! We continued to set new ECTC records, and, most importantly, we were very excited to bring back the in-person conference and give our great community the opportunity to meet again.

I would like to thank all our authors, speakers, invited panelists and plenary speakers, program committee members, exhibitors, sponsors, volunteers, attendees and IEEE EPS sponsoring organization who contributed and helped us achieve this success!

Here are some conference statistics that we would like to share with you:

- 1,509 attendees, which, given still uncertainties with the pandemic worldwide, have surpassed our expectations. While many of our colleagues could not join us this year, we still had 24 countries represented on-site.
- 362 technical papers, presented in 36 oral and 5 interactive presentation sessions, including one dedicated to students
- 10 Special Sessions, record numbers for our in-person conferences, with a wide range of very interesting topics and international participation of experts from industry and academia
- 16 professional development courses attended by 337 participants
- Strong international representation of our technical program with speakers from 21 different countries all around the world
- Record level of industry support with 45 corporate sponsorships
- 105 Technology Corner exhibit booths – all exhibitors contacted so far have already committed to return next year!
- Several receptions & networking opportunities that we hope you enjoyed

In addition to the regular daytime sessions and courses, the special sessions organized this year brought a wide range of topics relevant to our industry. Very well attended and with international participation, the special sessions brought

different perspectives on technology trends, applications, business trends, transformational strategies and career, diversity and workplace retention topics:

- ECTC Panel Session
 - Co-chaired by IEEE EPS President Kitty Pearsall of Boss Precision, US and Christopher Risso of Booz Allen Hamilton, US on "State-of-the Art Heterogeneous Integrated Packaging Program (SHIP – DoD Program)"
- ECTC Plenary Session
 - Co-chaired by Rozalia Beica of AT&S, China and Jean-Christophe Eloy of Yole Group, France, addressed "Digital Transformation – The Cornerstone of Future Semiconductor and Advanced Packaging Growth"
- IEEE EPS Seminar
 - Co-chaired by Yasumitsu Orii of Nagase, Japan and Shigenori Aoki of Lintec, Japan, on the "Interconnect Technologies for Chiplets"
- ECTC Emerging Technologies Technical Sub-Committee Special Session
 - Co-chaired by Chukwudi Okoro of Corning and Benson Chan of Binghamton University, US on "Micro-LED Display Technologies High Volume Manufacturing (HVM) Progress and Challenges"
- ECTC Assembly & Manufacturing Technologies Technical Sub-Committee Special Session
 - Chaired by Jan Vardaman of Techsearch, US on "Meeting Next Generation Packaging Challenges: Chiplets to Co-Packaged Optics"
- ECTC Heterogeneous Integration Roadmap Special Session
 - Chaired by Amr Helmy of University of Toronto, Canada that covered "Selected Topics of IEEE EPS Heterogeneous Integration (HIR)"
- ECTC/ITHERM Women's Panel
 - Co-chaired by Kim Yess of Brewer Science and Francoise Von Trapp, of 3D InCites, US and Cristina Amon of University of Toronto, Canada, on "Solving Diversification Challenges and Workforce Retention Issues"
- ECTC/ITHERM Young Professionals Special Session
 - Chaired by Yan Liu of Medtronic, Inc. and Adeel Bajwa of Kulicke & Soffa, US, a networking panel focus on career development for young professionals with the participation of IEEE EPS Board of Governors

The Heterogeneous Integration Roadmap Workshop, sponsored by the IEEE EPS, EDS and Photonics Societies together with SEMI and ASME EPPD, took place again at our conference with another packed audience this year as well. Thank you to the HIR committee for bringing another excellent workshop to ECTC.

Special thanks to our ECTC Keynote Speaker, Chris Koopmans, Chief Operations Officer with Marvel Technologies for his luncheon address on

"Accelerating the Power of Data Infrastructure with Cloud-Optimized Silicon." Mr. Koopmans described the transformation of Marvell Technology from a broad, consumer-oriented company to an industry-leading data infrastructure semiconductor solutions provider. Data infrastructure is a large, fast-growing market that power our global economy and is crucial in advancing our society. The presentation was a great overview of how companies need to transform themselves to data infrastructure and why and how Marvell accomplished that. His talk summarized how data infrastructure is converging into the cloud, the emerging cloud-optimized silicon era and the technology areas the industry must tackle to accelerate the power of data infrastructure with cloud-optimized silicon.

I would like to thank our Corporate and Media Sponsors:

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A big thank you to our volunteers, over 250 industry experts, Technical Program Committee members, Session Chairs and Executive Committee members.

Photos taken at the conference are now available on Flickr and can be [accessed here](#).

Finally, after a successful ECTC 2022, we would like to hear back from you so we can learn and plan the best event for next year. What worked well, what needs improvement, and what did you miss?

Please take a few minutes to answer our survey on [SurveyMonkey](#).

Next year's conference will be held 30 May – 2 June 2023, at the JW Marriott Orlando, Grande Lakes, Orlando, Florida, USA. We look forward to your support to help make the 73rd ECTC in 2023 a huge success.

On behalf of the entire Executive Committee, we thank you for your participation at the 72nd ECTC and we are looking forward to see you next year in Orlando!



Sincerely,

Rozalia Beica
General Chair, 2022 IEEE 72nd Electronic
Components and Technology Conference
AT&S - Shanghai, China

For more information on the 2022 ECTC visit www.ectc.net.

Also, see some of the ECTC [highlights](#).
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